



Attorney Docket No.: 042390.P7832

#15 Response (NE) [Signature] 3/8/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:  
Li-Shun Wang, John Chu  
Serial No.: 09/476,633  
Filed: December 31, 1999  
For: REMOVAL OF RESIDUE FROM A SUBSTRATE

Art Unit: 2823  
Examiner: Garcia, J.

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**RESPONSE TO FINAL OFFICE ACTION**

Box AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In connection with the Final Office Action (the "FOA") mailed on December 17, 2001 regarding the above-referenced Application, the Applicants respectfully request consideration of the following remarks.

**REMARKS**

In response to the FOA, no claims have been amended, no claims have been cancelled and no claims have been added. Accordingly, Claims 1-4 and 6-28 are pending.

Claims 1-4, 7, 9-12, 18, 19 and 26-28 are rejected under 35 U.S.C. §102(e). Claims 6, 8, 13, 14, 16, 17 and 20-22 are rejected under 35 U.S.C. §103(a). Claims 23-26 are rejected under 35 U.S.C. §112, first paragraph.

**I. 35 U.S.C. § 102(e): Rejection of Claims 1-4, 7, 9-12, 18, 19 and 26-28**

Claims 1-4, 7, 9-12, 18, 19 and 26- 28 are rejected under 35 U.S.C. § 102(e) as anticipated by U.S. Patent No. 6,159,858 to Kishii et al ("Kishii"). The Patent Office characterizes Kishii as "rinsing the surface of the metal plug with a solution comprising hydrogen peroxide." (see page 2, Office Action, mailed June 20, 2001). Applicants respectfully submit that the Patent Office continues to mischaracterize Kishii. Kishii does not disclose rinsing the surface of a plug; only cleaning of a substrate using a cleaning solution containing acid, hydrogen peroxide and water, so as to dissolve abrasive material is disclosed. (See Kishii, col. 14, lines 49-50, and